



#6/Amend B
(PATENT)
11/2/01

Docket No.: M4065.0127/P127-A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kie Y. Ahn, et al.

Application No.: 09/660,324

Filed: September 12, 2000

For: SILICON MULTI-CHIP MODULE
PACKAGING WITH INTEGRATED
PASSIVE COMPONENTS AND METHOD
OF MAKING

Group Art Unit: 2823

Examiner: E. Toledo

Please
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RESPONSE

Commissioner for Patents
Washington, DC 20231

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Technology Center 2800

Dear Sir:

In response to the Office Action dated September 26, 2001, applicants respectfully submit the following:

In the claims:

Please cancel claim 89.

Please amend claim 88 as follows:

88 (amended) A process for forming an interposer element for use as a chip carrier comprising the steps of:

providing an insulating layer on at least one surface of a silicon substrate; and